

Notice of References Cited	Application/Control No. 09/244,788	Applicant(s)/Patent Under Reexamination PARIKH, SUKETU A.	
	Examiner Thanhha Pham	Art Unit 2813	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-4,954,480	09-1990	Imanaka et al.	505/220
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
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	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Applied Materials Announces Breakthrough low K dielectric film for High-Speed Cooper Chips", Business Wire, 10/6/1998, pp 1072
	V	Zhao et al, "A Cu/Low-k Dual Damascene Interconnect for High Performance and Low Cost Integrated Circuits", VLSI Technology 1
	W	Merriam Webster's Collegiate Dictionary, 10 th edition, pp 811 & 1239
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.